

## Replacement Sheets

In the specification:

Page 68, paragraphs 1-3:

A1  
The present invention relates to a new urethane oligomer (A) and a resin composition comprising (A) and an unsaturated group containing polycarboxylic acid resin (B) that can be diluted with water and is excellent in providing a cured product and that is suitable for a solder resist and an interlayer dielectric layer because the cured product is excellent in flexibility, soldering-heat resistance or the like and allows a development with an organic solvent or a dilute alkali solution; a photosensitive resin composition suitable for an etching resist or a cover lay; and a photosensitive film obtained thereby.

In the claims:

Sub P2  
1. (Amended) A urethane oligomer (A) or the salt thereof obtained by reacting a polyol compound (a) with a polybasic acid anhydride (b-1) having two acid anhydride groups per molecule, a polyisocyanate compound (c) and a hydroxy compound having ethylenically unsaturated groups, successively.

A2  
2. (Amended) A urethane oligomer (A) according to Claim 1, wherein said polybasic acid anhydride (b-1) having at least two acid anhydride groups per molecule has an acid value of 200-1500mgKOH/g and the salt thereof.

3. (Amended) A urethane oligomer (A) according to claim 1 or 2, wherein said urethane oligomer (A) has a weight-average molecular weight of 1,000-100,000; and the salt thereof.

4. (Amended) A urethane oligomer (A) according to claim 1, wherein said urethane oligomer (A) has an acid value of 1-200mgKOH/g and the salt thereof.